ABSTRACT OF THE INVENTION

The present invention includes a method of providing a first substrate; forming an insulator over the first substrate; forming an opening in the insulator; forming a conductor over the insulator and in the opening; removing the conductor over the insulator with a first chemical-mechanical polish process to leave the conductor in the opening; and reducing thickness of the insulator with a second chemical-mechanical process to permit the conductor in the opening to protrude.

The present invention further includes a structure having such a conductor that protrudes.



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